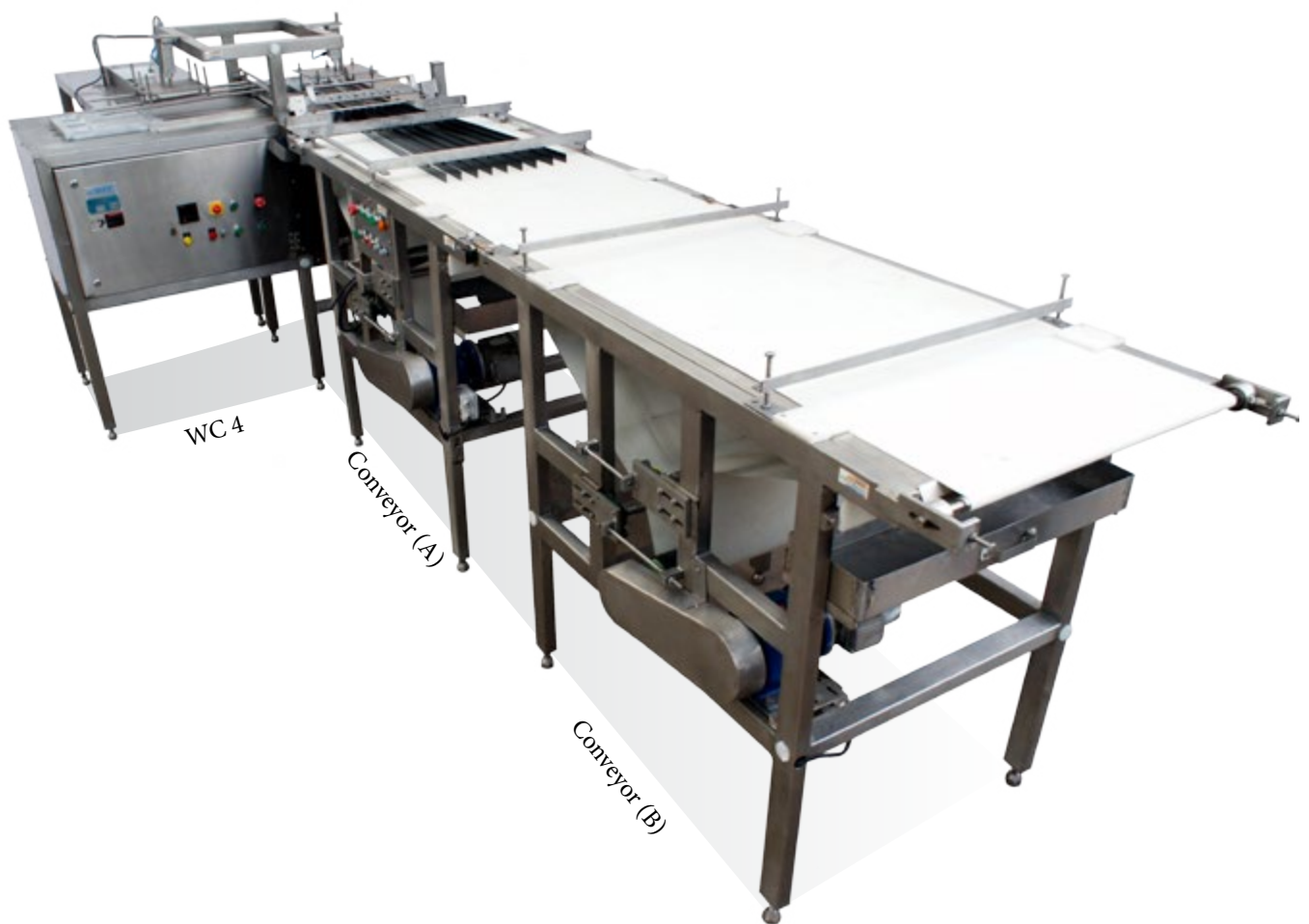


Wafer Distribution Device WFD - II



Better by Design...

Wafer Distribution (WFD) - Type II

This is a compact version of wafer cutting and mini distribution.

The cut wafer biscuit move directly and immediately from the cutting machine on to a conveyor with limited distribution.

Once the wafer biscuits are separated side to side, the conveyor carries the spread wafer biscuit forward on to chocolate coating line.

Conveyor (A) - Horizontal separation by strips guides.

Conveyor (B) - Vertical separation by inventor controlled belt speed.

The WFD - II

Consists of standard machines

- 1) Conveyor (A) & (B)
- 2) WC 4 - Wafer Cutting Machine

Optional Accessories

- 1) Outfeed cutting frame with divider guides suitable for each cut size can be ordered separately.

Limitation : Min. cutting width = 25 mm.



Technical Details

Machine Variables	WC 4*
Size of the Wafers (Possible)	290 x 460
Stack Height (mm)	70
Minimum Cutting Width (mm)	16
Cutting Wire (Spring Steel in mm)	0.5
Connected load (KW)	1.5
Dimension (mm)	
Length	1700
Width	1600
Height	1200
Net Weight (appx. kgs)	310
Shipping Volume (CBM)	4.5

Conveyor	(A) & (B)
Capacity / Book per min.	6
Connected load (KW)	0.37
Belt Width	1000 m
Dimension (mm)	
Length	1500
Width	1200
Height	1000
Net Weight (appx. kgs)	125
Shipping Volume (CBM)	2.0

*Modifications Reserved

We are constantly guided by our principle of offering our customers better and better machines; to give increased efficiency and higher levels of automation. The technical data and illustrations are subject to change without notice

R & D Engineers

A-41, IDA Kukatpally, Phase II, Road No. 4,
Via I.E. Gandhi Nagar, Hyderabad - 500 037
Phone : 23402682, 23079121, 23077985
Fax : 0091-040-23078668 Email: info@rndwafers.com

Local Contact :

Web : www.rndwafers.com